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Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details	
Product Status	Obsolete
Programmable Type	EE PLD
Delay Time tpd(1) Max	15 ns
Voltage Supply - Internal	4.75V ~ 5.25V
Number of Logic Elements/Blocks	6
Number of Macrocells	96
Number of Gates	1800
Number of I/O	52
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	68-LCC (J-Lead)
Supplier Device Package	68-PLCC (24x24)
Purchase URL	https://www.e-xfl.com/product-detail/intel/epm7096lc68-15

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

- Additional design entry and simulation support provided by EDIF 2 0 0 and 3 0 0 netlist files, library of parameterized modules (LPM), Verilog HDL, VHDL, and other interfaces to popular EDA tools from manufacturers such as Cadence, Exemplar Logic, Mentor Graphics, OrCAD, Synopsys, and VeriBest
- Programming support
 - Altera's Master Programming Unit (MPU) and programming hardware from third-party manufacturers program all MAX 7000 devices
 - The BitBlasterTM serial download cable, ByteBlasterMVTM parallel port download cable, and MasterBlasterTM serial/universal serial bus (USB) download cable program MAX 7000S devices

General Description

The MAX 7000 family of high-density, high-performance PLDs is based on Altera's second-generation MAX architecture. Fabricated with advanced CMOS technology, the EEPROM-based MAX 7000 family provides 600 to 5,000 usable gates, ISP, pin-to-pin delays as fast as 5 ns, and counter speeds of up to 175.4 MHz. MAX 7000S devices in the -5, -6, -7, and -10 speed grades as well as MAX 7000 and MAX 7000E devices in -5, -6, -7, -10P, and -12P speed grades comply with the PCI Special Interest Group (PCI SIG) *PCI Local Bus Specification, Revision 2.2.* See Table 3 for available speed grades.

Device	Speed Grade											
	-5	-6	-7	-10P	-10	-12P	-12	-15	-15T	-20		
EPM7032		✓	✓		✓		✓	✓	✓			
EPM7032S	✓	✓	✓		✓							
EPM7064		✓	✓		~		✓	✓				
EPM7064S	✓	✓	✓		~							
EPM7096			✓		~		✓	✓				
EPM7128E			✓	✓	~		✓	✓		✓		
EPM7128S		✓	✓		✓			✓				
EPM7160E				✓	✓		✓	✓		✓		
EPM7160S		✓	✓		~			✓				
EPM7192E						✓	✓	✓		✓		
EPM7192S			✓		✓			✓				
EPM7256E						✓	✓	✓		✓		
EPM7256S			✓		✓			✓				

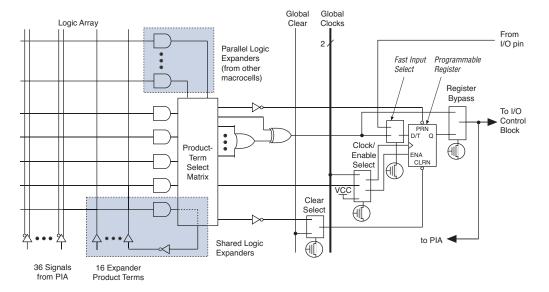
Each LAB is fed by the following signals:

- 36 signals from the PIA that are used for general logic inputs
- Global controls that are used for secondary register functions
- Direct input paths from I/O pins to the registers that are used for fast setup times for MAX 7000E and MAX 7000S devices

Macrocells

The MAX 7000 macrocell can be individually configured for either sequential or combinatorial logic operation. The macrocell consists of three functional blocks: the logic array, the product-term select matrix, and the programmable register. The macrocell of EPM7032, EPM7064, and EPM7096 devices is shown in Figure 3.

Figure 3. EPM7032, EPM7064 & EPM7096 Device Macrocell



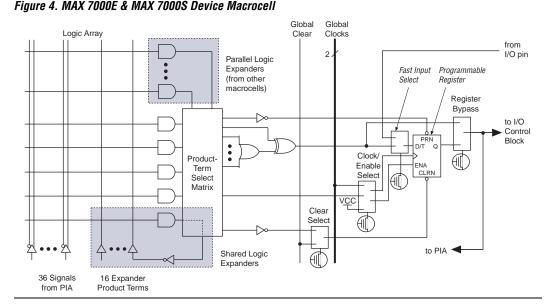


Figure 4 shows a MAX 7000E and MAX 7000S device macrocell.

Combinatorial logic is implemented in the logic array, which provides five product terms per macrocell. The product-term select matrix allocates these product terms for use as either primary logic inputs (to the OR and XOR gates) to implement combinatorial functions, or as secondary inputs to the macrocell's register clear, preset, clock, and clock enable control functions. Two kinds of expander product terms ("expanders") are available to supplement macrocell logic resources:

- Shareable expanders, which are inverted product terms that are fed back into the logic array
- Parallel expanders, which are product terms borrowed from adjacent macrocells

The Altera development system automatically optimizes product-term allocation according to the logic requirements of the design.

For registered functions, each macrocell flipflop can be individually programmed to implement D, T, JK, or SR operation with programmable clock control. The flipflop can be bypassed for combinatorial operation. During design entry, the designer specifies the desired flipflop type; the Altera development software then selects the most efficient flipflop operation for each registered function to optimize resource utilization.

Each programmable register can be clocked in three different modes:

- By a global clock signal. This mode achieves the fastest clock-tooutput performance.
- By a global clock signal and enabled by an active-high clock enable. This mode provides an enable on each flipflop while still achieving the fast clock-to-output performance of the global clock.
- By an array clock implemented with a product term. In this mode, the flipflop can be clocked by signals from buried macrocells or I/O pins.

In EPM7032, EPM7064, and EPM7096 devices, the global clock signal is available from a dedicated clock pin, GCLK1, as shown in Figure 1. In MAX 7000E and MAX 7000S devices, two global clock signals are available. As shown in Figure 2, these global clock signals can be the true or the complement of either of the global clock pins, GCLK1 or GCLK2.

Each register also supports asynchronous preset and clear functions. As shown in Figures 3 and 4, the product-term select matrix allocates product terms to control these operations. Although the product-term-driven preset and clear of the register are active high, active-low control can be obtained by inverting the signal within the logic array. In addition, each register clear function can be individually driven by the active-low dedicated global clear pin (GCLRn). Upon power-up, each register in the device will be set to a low state.

All MAX 7000E and MAX 7000S I/O pins have a fast input path to a macrocell register. This dedicated path allows a signal to bypass the PIA and combinatorial logic and be driven to an input D flipflop with an extremely fast (2.5 ns) input setup time.

Expander Product Terms

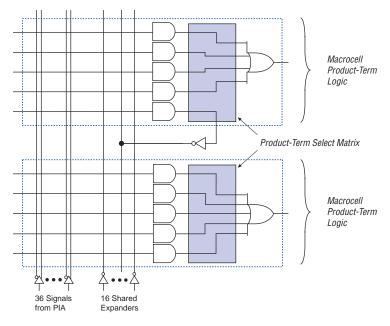
Although most logic functions can be implemented with the five product terms available in each macrocell, the more complex logic functions require additional product terms. Another macrocell can be used to supply the required logic resources; however, the MAX 7000 architecture also allows both shareable and parallel expander product terms ("expanders") that provide additional product terms directly to any macrocell in the same LAB. These expanders help ensure that logic is synthesized with the fewest possible logic resources to obtain the fastest possible speed.

Shareable Expanders

Each LAB has 16 shareable expanders that can be viewed as a pool of uncommitted single product terms (one from each macrocell) with inverted outputs that feed back into the logic array. Each shareable expander can be used and shared by any or all macrocells in the LAB to build complex logic functions. A small delay (t_{SEXP}) is incurred when shareable expanders are used. Figure 5 shows how shareable expanders can feed multiple macrocells.

Figure 5. Shareable Expanders

Shareable expanders can be shared by any or all macrocells in an LAB.



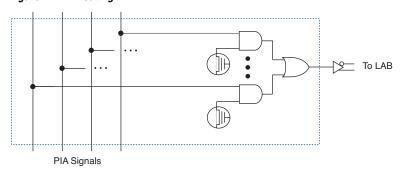
Parallel Expanders

Parallel expanders are unused product terms that can be allocated to a neighboring macrocell to implement fast, complex logic functions. Parallel expanders allow up to 20 product terms to directly feed the macrocell OR logic, with five product terms provided by the macrocell and 15 parallel expanders provided by neighboring macrocells in the LAB.

Programmable Interconnect Array

Logic is routed between LABs via the programmable interconnect array (PIA). This global bus is a programmable path that connects any signal source to any destination on the device. All MAX 7000 dedicated inputs, I/O pins, and macrocell outputs feed the PIA, which makes the signals available throughout the entire device. Only the signals required by each LAB are actually routed from the PIA into the LAB. Figure 7 shows how the PIA signals are routed into the LAB. An EEPROM cell controls one input to a 2-input AND gate, which selects a PIA signal to drive into the LAB.

Figure 7. PIA Routing



While the routing delays of channel-based routing schemes in masked or FPGAs are cumulative, variable, and path-dependent, the MAX 7000 PIA has a fixed delay. The PIA thus eliminates skew between signals and makes timing performance easy to predict.

I/O Control Blocks

The I/O control block allows each I/O pin to be individually configured for input, output, or bidirectional operation. All I/O pins have a tri-state buffer that is individually controlled by one of the global output enable signals or directly connected to ground or V_{CC}. Figure 8 shows the I/O control block for the MAX 7000 family. The I/O control block of EPM7032, EPM7064, and EPM7096 devices has two global output enable signals that are driven by two dedicated active-low output enable pins (OE1 and OE2). The I/O control block of MAX 7000E and MAX 7000S devices has six global output enable signals that are driven by the true or complement of two output enable signals, a subset of the I/O pins, or a subset of the I/O macrocells.



For more information on using the Jam language, refer to AN 122: Using Jam STAPL for ISP & ICR via an Embedded Processor.

The ISP circuitry in MAX 7000S devices is compatible with IEEE Std. 1532 specification. The IEEE Std. 1532 is a standard developed to allow concurrent ISP between multiple PLD vendors.

Programming Sequence

During in-system programming, instructions, addresses, and data are shifted into the MAX 7000S device through the TDI input pin. Data is shifted out through the TDO output pin and compared against the expected data.

Programming a pattern into the device requires the following six ISP stages. A stand-alone verification of a programmed pattern involves only stages 1, 2, 5, and 6.

- Enter ISP. The enter ISP stage ensures that the I/O pins transition smoothly from user mode to ISP mode. The enter ISP stage requires 1 ms.
- 2. *Check ID*. Before any program or verify process, the silicon ID is checked. The time required to read this silicon ID is relatively small compared to the overall programming time.
- 3. *Bulk Erase*. Erasing the device in-system involves shifting in the instructions to erase the device and applying one erase pulse of 100 ms.
- Program. Programming the device in-system involves shifting in the address and data and then applying the programming pulse to program the EEPROM cells. This process is repeated for each EEPROM address.
- Verify. Verifying an Altera device in-system involves shifting in addresses, applying the read pulse to verify the EEPROM cells, and shifting out the data for comparison. This process is repeated for each EEPROM address.
- 6. Exit ISP. An exit ISP stage ensures that the I/O pins transition smoothly from ISP mode to user mode. The exit ISP stage requires 1 ms.

Programmable Speed/Power Control

MAX 7000 devices offer a power-saving mode that supports low-power operation across user-defined signal paths or the entire device. This feature allows total power dissipation to be reduced by 50% or more, because most logic applications require only a small fraction of all gates to operate at maximum frequency.

The designer can program each individual macrocell in a MAX 7000 device for either high-speed (i.e., with the Turbo BitTM option turned on) or low-power (i.e., with the Turbo Bit option turned off) operation. As a result, speed-critical paths in the design can run at high speed, while the remaining paths can operate at reduced power. Macrocells that run at low power incur a nominal timing delay adder (t_{LPA}) for the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , and t_{SEXP} , t_{ACL} , and t_{CPPW} parameters.

Output Configuration

MAX 7000 device outputs can be programmed to meet a variety of system-level requirements.

MultiVolt I/O Interface

MAX 7000 devices—except 44-pin devices—support the MultiVolt I/O interface feature, which allows MAX 7000 devices to interface with systems that have differing supply voltages. The 5.0-V devices in all packages can be set for 3.3-V or 5.0-V I/O pin operation. These devices have one set of VCC pins for internal operation and input buffers (VCCINT), and another set for I/O output drivers (VCCIO).

The VCCINT pins must always be connected to a 5.0-V power supply. With a 5.0-V $V_{\rm CCINT}$ level, input voltage thresholds are at TTL levels, and are therefore compatible with both 3.3-V and 5.0-V inputs.

The VCCIO pins can be connected to either a 3.3-V or a 5.0-V power supply, depending on the output requirements. When the VCCIO pins are connected to a 5.0-V supply, the output levels are compatible with 5.0-V systems. When $V_{\rm CCIO}$ is connected to a 3.3-V supply, the output high is 3.3 V and is therefore compatible with 3.3-V or 5.0-V systems. Devices operating with $V_{\rm CCIO}$ levels lower than 4.75 V incur a nominally greater timing delay of $t_{\rm OD2}$ instead of $t_{\rm OD1}$.

Open-Drain Output Option (MAX 7000S Devices Only)

MAX 7000S devices provide an optional open-drain (functionally equivalent to open-collector) output for each I/O pin. This open-drain output enables the device to provide system-level control signals (e.g., interrupt and write enable signals) that can be asserted by any of several devices. It can also provide an additional wired-OR plane.

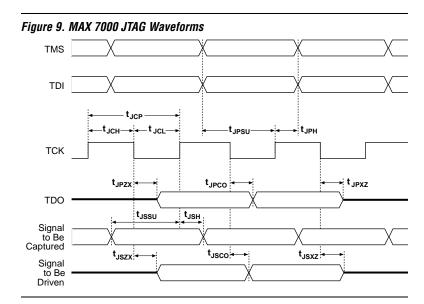


Figure 9 shows the timing requirements for the JTAG signals.

Table 12 shows the JTAG timing parameters and values for MAX 7000S devices.

Table 1	2. JTAG Timing Parameters & Values for MAX 70	00S De	vices	
Symbol	Parameter	Min	Max	Unit
t _{JCP}	TCK clock period	100		ns
t _{JCH}	TCK clock high time	50		ns
t _{JCL}	TCK clock low time	50		ns
t _{JPSU}	JTAG port setup time	20		ns
t _{JPH}	JTAG port hold time	45		ns
t _{JPCO}	JTAG port clock to output		25	ns
t _{JPZX}	JTAG port high impedance to valid output		25	ns
t _{JPXZ}	JTAG port valid output to high impedance		25	ns
t _{JSSU}	Capture register setup time	20		ns
t _{JSH}	Capture register hold time	45		ns
t _{JSCO}	Update register clock to output		25	ns
t _{JSZX}	Update register high impedance to valid output		25	ns
t _{JSXZ}	Update register valid output to high impedance		25	ns



For more information, see *Application Note* 39 (*IEEE 1149.1 (JTAG) Boundary-Scan Testing in Altera Devices*).

Tables 19 through 26 show the MAX 7000 and MAX 7000E AC operating conditions.

Symbol	Parameter	Conditions	-6 Speed Grade		-7 Spee	Unit	
			Min	Max	Min	Max	
t _{PD1}	Input to non-registered output	C1 = 35 pF		6.0		7.5	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		6.0		7.5	ns
t _{SU}	Global clock setup time		5.0		6.0		ns
t _H	Global clock hold time		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input	(2)	2.5		3.0		ns
t _{FH}	Global clock hold time of fast input	(2)	0.5		0.5		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF		4.0		4.5	ns
t _{CH}	Global clock high time		2.5		3.0		ns
t _{CL}	Global clock low time		2.5		3.0		ns
t _{ASU}	Array clock setup time		2.5		3.0		ns
t _{AH}	Array clock hold time		2.0		2.0		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF		6.5		7.5	ns
t _{ACH}	Array clock high time		3.0		3.0		ns
t _{ACL}	Array clock low time		3.0		3.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(3)	3.0		3.0		ns
t _{ODH}	Output data hold time after clock	C1 = 35 pF (4)	1.0		1.0		ns
t _{CNT}	Minimum global clock period			6.6		8.0	ns
f _{CNT}	Maximum internal global clock frequency	(5)	151.5		125.0		MHz
t _{ACNT}	Minimum array clock period			6.6		8.0	ns
f _{ACNT}	Maximum internal array clock frequency	(5)	151.5		125.0		MHz
f _{MAX}	Maximum clock frequency	(6)	200		166.7		MHz

Symbol	Parameter	Conditions		Speed	Grade		Unit
			MAX 700	OE (-10P)		00 (-10) DOE (-10)	
			Min	Max	Min	Max	
t _{IN}	Input pad and buffer delay			0.5		1.0	ns
t _{IO}	I/O input pad and buffer delay			0.5		1.0	ns
t _{FIN}	Fast input delay	(2)		1.0		1.0	ns
t _{SEXP}	Shared expander delay			5.0		5.0	ns
t _{PEXP}	Parallel expander delay			0.8		0.8	ns
t_{LAD}	Logic array delay			5.0		5.0	ns
t _{LAC}	Logic control array delay			5.0		5.0	ns
t _{IOE}	Internal output enable delay	(2)		2.0		2.0	ns
t _{OD1}	Output buffer and pad delay Slow slew rate = off V _{CCIO} = 5.0 V	C1 = 35 pF		1.5		2.0	ns
t _{OD2}	Output buffer and pad delay Slow slew rate = off V _{CCIO} = 3.3 V	C1 = 35 pF (7)		2.0		2.5	ns
t _{OD3}	Output buffer and pad delay Slow slew rate = on V _{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF (2)		5.5		6.0	ns
t _{ZX1}	Output buffer enable delay Slow slew rate = off V _{CCIO} = 5.0 V	C1 = 35 pF		5.0		5.0	ns
t _{ZX2}	Output buffer enable delay Slow slew rate = off V _{CCIO} = 3.3 V	C1 = 35 pF (7)		5.5		5.5	ns
t _{ZX3}	Output buffer enable delay Slow slew rate = on V _{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF (2)		9.0		9.0	ns
t_{XZ}	Output buffer disable delay	C1 = 5 pF		5.0		5.0	ns
t_{SU}	Register setup time		2.0		3.0		ns
t_H	Register hold time		3.0		3.0		ns
t _{FSU}	Register setup time of fast input	(2)	3.0		3.0		ns
t_{FH}	Register hold time of fast input	(2)	0.5		0.5		ns
t _{RD}	Register delay			2.0		1.0	ns
t _{COMB}	Combinatorial delay			2.0		1.0	ns
t _{IC}	Array clock delay			5.0		5.0	ns
t_{EN}	Register enable time			5.0		5.0	ns
t _{GLOB}	Global control delay			1.0		1.0	ns
t _{PRE}	Register preset time			3.0		3.0	ns
t _{CLR}	Register clear time			3.0		3.0	ns
t _{PIA}	PIA delay			1.0		1.0	ns
t _{LPA}	Low-power adder	(8)		11.0		11.0	ns

Table 24	4. MAX 7000 & MAX 7000E Int	ernal Timing Parame	eters Note	e (1)			
Symbol	Parameter	Conditions		Speed	Grade		Unit
			MAX 700	OE (-12P)		000 (-12) 00E (-12)	
			Min	Max	Min	Max	
t _{IN}	Input pad and buffer delay			1.0		2.0	ns
t _{IO}	I/O input pad and buffer delay			1.0		2.0	ns
t _{FIN}	Fast input delay	(2)		1.0		1.0	ns
t _{SEXP}	Shared expander delay			7.0		7.0	ns
t _{PEXP}	Parallel expander delay			1.0		1.0	ns
t _{LAD}	Logic array delay			7.0		5.0	ns
t _{LAC}	Logic control array delay			5.0		5.0	ns
t _{IOE}	Internal output enable delay	(2)		2.0		2.0	ns
t _{OD1}	Output buffer and pad delay Slow slew rate = off V _{CCIO} = 5.0 V	C1 = 35 pF		1.0		3.0	ns
t _{OD2}	Output buffer and pad delay Slow slew rate = off V _{CCIO} = 3.3 V	C1 = 35 pF (7)		2.0		4.0	ns
t _{OD3}	Output buffer and pad delay Slow slew rate = on V _{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF (2)		5.0		7.0	ns
t _{ZX1}	Output buffer enable delay Slow slew rate = off V _{CCIO} = 5.0 V	C1 = 35 pF		6.0		6.0	ns
t _{ZX2}	Output buffer enable delay Slow slew rate = off V _{CCIO} = 3.3 V	C1 = 35 pF (7)		7.0		7.0	ns
t _{ZX3}	Output buffer enable delay Slow slew rate = on V _{CCIO} = 5.0 V or 3.3 V	C1 = 35 pF (2)		10.0		10.0	ns
t_{XZ}	Output buffer disable delay	C1 = 5 pF		6.0		6.0	ns
t _{SU}	Register setup time		1.0		4.0		ns
t _H	Register hold time		6.0		4.0		ns
t _{FSU}	Register setup time of fast input	(2)	4.0		2.0		ns
t _{FH}	Register hold time of fast input	(2)	0.0		2.0		ns
t _{RD}	Register delay			2.0		1.0	ns
t _{COMB}	Combinatorial delay			2.0		1.0	ns
t _{IC}	Array clock delay			5.0		5.0	ns
t _{EN}	Register enable time			7.0		5.0	ns
t _{GLOB}	Global control delay			2.0		0.0	ns
t _{PRE}	Register preset time			4.0		3.0	ns
t _{CLR}	Register clear time			4.0		3.0	ns
t _{PIA}	PIA delay			1.0		1.0	ns
t _{LPA}	Low-power adder	(8)		12.0		12.0	ns

Table 2	Table 28. EPM7032S Internal Timing Parameters Note (1)												
Symbol	Parameter	Conditions				Speed	Grade				Unit		
			-	-5 -6				7	-1	0			
			Min	Max	Min	Max	Min	Max	Min	Max			
t _{PIA}	PIA delay	(7)		1.1		1.1		1.4		1.0	ns		
t_{LPA}	Low-power adder	(8)		12.0		10.0		10.0		11.0	ns		

Notes to tables:

- These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The f_{MAX} values represent the highest frequency for pipelined data.
- (6) Operating conditions: $V_{CCIO} = 3.3 \text{ V} \pm 10\%$ for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , t_{SEXP} , $\mathbf{t_{ACL}}$, and $\mathbf{t_{CPPW}}$ parameters for macrocells running in the low-power mode.

Tables 29 and 30 show the EPM7064S AC operating conditions.

Table 2	9. EPM7064S External Timi	ing Parameters	(Part	1 of 2)	No	nte (1)						
Symbol	Parameter	Conditions	Speed Grade									
			-	5	-	6	-	7	-1	10		
			Min	Max	Min	Max	Min	Max	Min	Max		
t _{PD1}	Input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns	
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		5.0		6.0		7.5		10.0	ns	
t _{SU}	Global clock setup time		2.9		3.6		6.0		7.0		ns	
t _H	Global clock hold time		0.0		0.0		0.0		0.0		ns	
t _{FSU}	Global clock setup time of fast input		2.5		2.5		3.0		3.0		ns	
t _{FH}	Global clock hold time of fast input		0.0		0.0		0.5		0.5		ns	
t _{CO1}	Global clock to output delay	C1 = 35 pF		3.2		4.0		4.5		5.0	ns	
t _{CH}	Global clock high time		2.0		2.5		3.0		4.0		ns	
t _{CL}	Global clock low time		2.0		2.5		3.0		4.0		ns	
t _{ASU}	Array clock setup time		0.7		0.9		3.0		2.0		ns	
t _{AH}	Array clock hold time		1.8		2.1		2.0		3.0		ns	

Table 29. EPM7064S External Timing Parameters (Part 2 of 2) Note (1)												
Symbol	Parameter	Conditions	Speed Grade									
			-	-5 -6		-7		-10				
			Min	Max	Min	Max	Min	Max	Min	Max		
t _{ACO1}	Array clock to output delay	C1 = 35 pF		5.4		6.7		7.5		10.0	ns	
t _{ACH}	Array clock high time		2.5		2.5		3.0		4.0		ns	
t _{ACL}	Array clock low time		2.5		2.5		3.0		4.0		ns	
t _{CPPW}	Minimum pulse width for clear and preset	(2)	2.5		2.5		3.0		4.0		ns	
t _{ODH}	Output data hold time after clock	C1 = 35 pF (3)	1.0		1.0		1.0		1.0		ns	
t _{CNT}	Minimum global clock period			5.7		7.1		8.0		10.0	ns	
f _{CNT}	Maximum internal global clock frequency	(4)	175.4		140.8		125.0		100.0		MHz	
t _{ACNT}	Minimum array clock period			5.7		7.1		8.0		10.0	ns	
f _{ACNT}	Maximum internal array clock frequency	(4)	175.4		140.8		125.0		100.0		MHz	
f _{MAX}	Maximum clock frequency	(5)	250.0		200.0		166.7		125.0		MHz	

Table 3	O. EPM7064\$ Internal Tim	ing Parameters	(Part	1 of 2)	No	te (1)					
Symbol	Parameter	Conditions				Speed	Grade				Unit
			-	5	-	6	-7		-10		
			Min	Max	Min	Max	Min	Max	Min	Max	
t_{IN}	Input pad and buffer delay			0.2		0.2		0.5		0.5	ns
t _{IO}	I/O input pad and buffer delay			0.2		0.2		0.5		0.5	ns
t _{FIN}	Fast input delay			2.2		2.6		1.0		1.0	ns
t _{SEXP}	Shared expander delay			3.1		3.8		4.0		5.0	ns
t _{PEXP}	Parallel expander delay			0.9		1.1		0.8		0.8	ns
t_{LAD}	Logic array delay			2.6		3.2		3.0		5.0	ns
t _{LAC}	Logic control array delay			2.5		3.2		3.0		5.0	ns
t _{IOE}	Internal output enable delay			0.7		0.8		2.0		2.0	ns
t _{OD1}	Output buffer and pad delay	C1 = 35 pF		0.2		0.3		2.0		1.5	ns
t _{OD2}	Output buffer and pad delay	C1 = 35 pF (6)		0.7		0.8		2.5		2.0	ns
t _{OD3}	Output buffer and pad delay	C1 = 35 pF		5.2		5.3		7.0		5.5	ns
t_{ZX1}	Output buffer enable delay	C1 = 35 pF		4.0		4.0		4.0		5.0	ns
t _{ZX2}	Output buffer enable delay	C1 = 35 pF (6)		4.5		4.5		4.5		5.5	ns
t _{ZX3}	Output buffer enable delay	C1 = 35 pF		9.0		9.0		9.0		9.0	ns
t_{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		4.0		4.0		5.0	ns
t _{SU}	Register setup time		0.8		1.0		3.0		2.0		ns
t _H	Register hold time		1.7		2.0		2.0		3.0		ns

Table 33. EPM7160S External Timing Parameters (Part 2 of 2) Note (1)											
Symbol	Parameter	Conditions				Speed	Grade	}			Unit
			-	-6 -7 -10 -15							
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{ACNT}	Minimum array clock period			6.7		8.2		10.0		13.0	ns
f _{ACNT}	Maximum internal array clock frequency	(4)	149.3		122.0		100.0		76.9		MHz
f _{MAX}	Maximum clock frequency	(5)	166.7		166.7		125.0		100.0		MHz

Table 34. EPM7160S Internal Timing Parameters (Part 1 of 2) Note (1)												
Symbol	Parameter	Conditions				Speed	Grade				Unit	
			-	6	-	7	-1	10	-1	15		
			Min	Max	Min	Max	Min	Max	Min	Max		
t _{IN}	Input pad and buffer delay			0.2		0.3		0.5		2.0	ns	
t _{IO}	I/O input pad and buffer delay			0.2		0.3		0.5		2.0	ns	
t _{FIN}	Fast input delay			2.6		3.2		1.0		2.0	ns	
t _{SEXP}	Shared expander delay			3.6		4.3		5.0		8.0	ns	
t _{PEXP}	Parallel expander delay			1.0		1.3		0.8		1.0	ns	
t_{LAD}	Logic array delay			2.8		3.4		5.0		6.0	ns	
t _{LAC}	Logic control array delay			2.8		3.4		5.0		6.0	ns	
t _{IOE}	Internal output enable delay			0.7		0.9		2.0		3.0	ns	
t _{OD1}	Output buffer and pad delay	C1 = 35 pF		0.4		0.5		1.5		4.0	ns	
t _{OD2}	Output buffer and pad delay	C1 = 35 pF (6)		0.9		1.0		2.0		5.0	ns	
t _{OD3}	Output buffer and pad delay	C1 = 35 pF		5.4		5.5		5.5		8.0	ns	
t_{ZX1}	Output buffer enable delay	C1 = 35 pF		4.0		4.0		5.0		6.0	ns	
t _{ZX2}	Output buffer enable delay	C1 = 35 pF (6)		4.5		4.5		5.5		7.0	ns	
t _{ZX3}	Output buffer enable delay	C1 = 35 pF		9.0		9.0		9.0		10.0	ns	
t _{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		4.0		5.0		6.0	ns	
t _{SU}	Register setup time		1.0		1.2		2.0		4.0		ns	
t _H	Register hold time		1.6		2.0		3.0		4.0		ns	
t _{FSU}	Register setup time of fast input		1.9		2.2		3.0		2.0		ns	
t _{FH}	Register hold time of fast input		0.6		0.8		0.5		1.0		ns	
t_{RD}	Register delay			1.3		1.6		2.0		1.0	ns	
t _{COMB}	Combinatorial delay			1.0		1.3		2.0		1.0	ns	
t _{IC}	Array clock delay			2.9		3.5		5.0		6.0	ns	
t _{EN}	Register enable time			2.8		3.4		5.0		6.0	ns	
t _{GLOB}	Global control delay			2.0		2.4		1.0		1.0	ns	
t _{PRE}	Register preset time			2.4		3.0		3.0		4.0	ns	

Table 3	Table 34. EPM7160S Internal Timing Parameters (Part 2 of 2) Note (1)										
Symbol	Parameter	Conditions		Speed Grade Ui						Unit	
			-6 -7			-10		-15			
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{CLR}	Register clear time			2.4		3.0		3.0		4.0	ns
t _{PIA}	PIA delay	(7)		1.6		2.0		1.0		2.0	ns
t _{LPA}	Low-power adder	(8)		11.0		10.0		11.0		13.0	ns

Notes to tables:

- These values are specified under the recommended operating conditions shown in Table 14. See Figure 13 for more information on switching waveforms.
- (2) This minimum pulse width for preset and clear applies for both global clear and array controls. The t_{LPA} parameter must be added to this minimum width if the clear or reset signal incorporates the t_{LAD} parameter into the signal path.
- (3) This parameter is a guideline that is sample-tested only and is based on extensive device characterization. This parameter applies for both global and array clocking.
- (4) These parameters are measured with a 16-bit loadable, enabled, up/down counter programmed into each LAB.
- (5) The f_{MAX} values represent the highest frequency for pipelined data.
- (6) Operating conditions: $V_{CCIO} = 3.3 \text{ V} \pm 10\%$ for commercial and industrial use.
- (7) For EPM7064S-5, EPM7064S-6, EPM7128S-6, EPM7160S-6, EPM7160S-7, EPM7192S-7, and EPM7256S-7 devices, these values are specified for a PIA fan-out of one LAB (16 macrocells). For each additional LAB fan-out in these devices, add an additional 0.1 ns to the PIA timing value.
- (8) The t_{LPA} parameter must be added to the t_{LAD} , t_{LAC} , t_{IC} , t_{EN} , t_{SEXP} , t_{ACL} , and t_{CPPW} parameters for macrocells running in the low-power mode.

Tables 35 and 36 show the EPM7192S AC operating conditions.

Table 35. EPM7192S External Timing Parameters (Part 1 of 2) Note (1)									
Symbol	Parameter	Conditions	Speed Grade						
			-7		-10		-15		•
			Min	Max	Min	Max	Min	Max	1
t _{PD1}	Input to non-registered output	C1 = 35 pF		7.5		10.0		15.0	ns
t _{PD2}	I/O input to non-registered output	C1 = 35 pF		7.5		10.0		15.0	ns
t _{SU}	Global clock setup time		4.1		7.0		11.0		ns
t _H	Global clock hold time		0.0		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input		3.0		3.0		3.0		ns
t _{FH}	Global clock hold time of fast input		0.0		0.5		0.0		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF		4.7		5.0		8.0	ns
t _{CH}	Global clock high time		3.0		4.0		5.0		ns
t _{CL}	Global clock low time		3.0		4.0		5.0		ns
t _{ASU}	Array clock setup time		1.0		2.0		4.0		ns

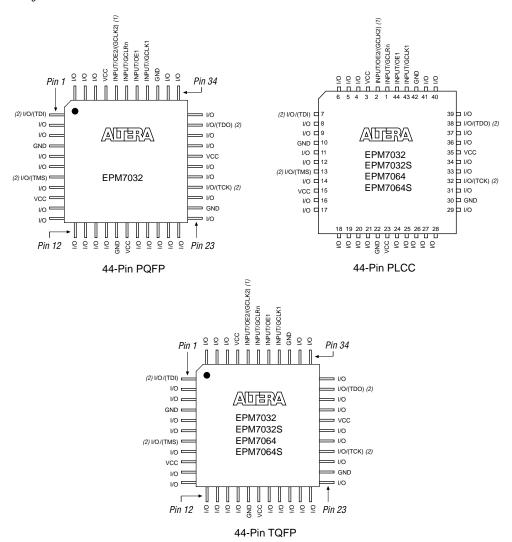
Table 39. MAX 7000 I _{CC} Equation Constants							
Device	Α	В	С				
EPM7032	1.87	0.52	0.144				
EPM7064	1.63	0.74	0.144				
EPM7096	1.63	0.74	0.144				
EPM7128E	1.17	0.54	0.096				
EPM7160E	1.17	0.54	0.096				
EPM7192E	1.17	0.54	0.096				
EPM7256E	1.17	0.54	0.096				
EPM7032S	0.93	0.40	0.040				
EPM7064S	0.93	0.40	0.040				
EPM7128S	0.93	0.40	0.040				
EPM7160S	0.93	0.40	0.040				
EPM7192S	0.93	0.40	0.040				
EPM7256S	0.93	0.40	0.040				

This calculation provides an I_{CC} estimate based on typical conditions using a pattern of a 16-bit, loadable, enabled, up/down counter in each LAB with no output load. Actual I_{CC} values should be verified during operation because this measurement is sensitive to the actual pattern in the device and the environmental operating conditions.

Figures 16 through 22 show the package pin-out diagrams for MAX 7000 devices.

Figure 16. 44-Pin Package Pin-Out Diagram

Package outlines not drawn to scale.



Notes:

- (1) The pin functions shown in parenthesis are only available in MAX 7000E and MAX 7000S devices.
- (2) JTAG ports are available in MAX 7000S devices only.

Revision History

The information contained in the *MAX 7000 Programmable Logic Device Family Data Sheet* version 6.7 supersedes information published in previous versions. The following changes were made in the *MAX 7000 Programmable Logic Device Family Data Sheet* version 6.7:

Version 6.7

The following changes were made in the MAX 7000 Programmable Logic Device Family Data Sheet version 6.7:

Reference to AN 88: Using the Jam Language for ISP & ICR via an Embedded Processor has been replaced by AN 122: Using Jam STAPL for ISP & ICR via an Embedded Processor.

Version 6.6

The following changes were made in the MAX 7000 Programmable Logic Device Family Data Sheet version 6.6:

- Added Tables 6 through 8.
- Added "Programming Sequence" section on page 17 and "Programming Times" section on page 18.

Version 6.5

The following changes were made in the MAX 7000 Programmable Logic Device Family Data Sheet version 6.5:

Updated text on page 16.

Version 6.4

The following changes were made in the MAX 7000 Programmable Logic Device Family Data Sheet version 6.4:

Added Note (5) on page 28.

Version 6.3

The following changes were made in the MAX 7000 Programmable Logic Device Family Data Sheet version 6.3:

■ Updated the "Open-Drain Output Option (MAX 7000S Devices Only)" section on page 20.

